Overview

HP Z4 G5 Workstation



Front

- 1. Integrated Front Handle
- 2. Power Button
- 3. HDD Activity LED
- 4. Headphone/microphone combo

¹Only 1 external 5.25" drive configurable from factory ²Premium Front IO is shown on photography Front I/O Premium²: 2 SuperSpeed USB Type-CTM 20 Gbps signaling rate (USB Power Delivery 3.0), 2 SuperSpeed USB Type-A 5 Gbps signaling rate [leftmost Type-A port supports BC1.2 (Battery Charging)]

Front I/O Entry:

4 SuperSpeed USB Type-A 5 Gbps signaling rate [leftmost Type-A ports supports BC1.2 (Battery Charging)]

- 6. SD Card Reader
- 7. 2x External 5.25" bay¹

Overview



Internal View

- 1. 1 Intel[®] Xeon[®] Processor (Sapphire Rapids)
- 2. 8 DIMM slots for DDR5 ECC Memory
- 3. Slot 1: PCle x16 Gen5
 - Slot 2: PCIe x4 Gen4
 - Slot 3: PCIe x4 Gen4
 - Slot 4: PCIe x16 Gen4
 - Slot 5: PCIe x16 Gen4
- 4. 2 PCIe x4 Gen4 configurable with M.2 SSDs

- 5. 5 SATA ports
- 6. 3 Internal USB Ports. 1 single USB2.0 port, 1 dual USB2.0 port, 1 USB3.0 port (for the SD card reader)
- 7. 2 Internal 3.5" bays
- 8. 2 External 5.25" bays
- 9. Choice of 525W, 775W, or 1125W 90% Efficient Power Supplies
- 10. 1 Internal NVMe connector to front removable M.2 carrier

Overview



Rear View

- 1. Integrated Rear Handle
- Power Connector (Choice of 525W, 775W, or 1125W 90% Efficient. Flex I/O Module (optional) 2. **Power Supplies)**
- 3. **External Antenna**
- **Rear Power Button** 4.
- 5. Audio In/Out

- 6. Manageability Port (optional)
- 8. 1 RJ-45 Integrated LAN Port (1GbE AMT)
- 9. 6 SuperSpeed USB Type-A 5Gbps Signaling Rate

Overview

Form Factor

Operating Systems

Preinstalled:

Tower

- Windows 11 Pro for Workstations²
- Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade).^{2,3}
- Ubuntu Linux 22.04⁴
- HP Linux[®]-ready (minimal OS ready for customer OS installation)⁵

License Only:

 Red Hat[®] Enterprise Linux[®] Desktop Workstation (includes paper license with 1 year support; no preinstalled OS)⁶

Supported:

- Windows 11, version 22H2, 21H2²
- Windows 10, version 22H2, 21H2²
- Red Hat® Enterprise Linux® Workstation 8 & 96
- SUSE Linux® Enterprise Desktop 15⁶
- Ubuntu 20.04 & 22.04 LTS⁵

Web-supported only:

- Windows 11 Enterprise^{2,1}
- Windows 10 Enterprise^{2,1}

¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other versior You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

⁵A certified preloaded version of Ubuntu[®] 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁶For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Overview

Processors

				Frequenc	у		Max Memo	ory Speed		
			(GHz)				(MT/s)			
Name ¹	Cores	Threads	Base Clock Speed	Intel® Turbo Boost Max All-Core Frequency ²	Intel® Turbo Boost Max Single-Core Frequency ²	Cache (MB)	1 DIMM per Channel	2 DIMM per Channel	TDP (W)	
Intel® Xeon® W7-2495X	24	48	2.5	3.3	4.6	45	4800	4400	225	
Intel® Xeon® W7-2475X	20	40	2.6	3.4	4.6	37.5	4800	4400	225	
Intel® Xeon® W5-2465X	16	32	3.1	3.7	4.5	33.75	4800	4400	200	
Intel® Xeon® W5-2455X	12	24	3.2	3.9	4.4	30	4800	4400	200	
Intel® Xeon® W5-2445	10	20	3.1	4.0	4.4	26.25	4800	4400	175	
Intel® Xeon® W3-2435	8	16	3.1	4.0	4.3	22.5	4400	4400	165	
Intel® Xeon® W3-2425	6	12	3.0	3.7	4.2	15	4400	4400	130	
Intel® Xeon® W3-2423	6	12	2.0	3.1	4.0	15	4400	4400	110	

Notes:

Xeon W-2400 processors all feature Intel® vPro® Technology³

- Xeon W-2400 processors all support Hyper-Threading
- Xeon W-2400 processors do not offer integrated graphics

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance

² Intel Turbo Boost Max (ITBM) performance varies depending on hardware, software, and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

³ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

Color	Black
Convertibility	No
Expansion Slots (see system board section for more details)	 Slot 1: PCle x16 Gen5 Slot 2: PCle x4 Gen4 Slot 3: PCle x4 Gen4 Slot 4: PCle x16 Gen4

Slot 4: PCIe x16 Gen4
Slot 5: PCIe x16 Gen4

Overview	
Expansion Bays (see storage section for more details)	1 internal 3.5" bays 2 external 5.25" bays
Front I/O	Front I/O Premium: 2 SuperSpeed USB Type-C TM 20 Gbps signaling rate (USB Power Delivery 3.0), 2 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD card reader (optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]
	Front I/O Entry: 4 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD carc reader (optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]
Internal I/O [5]	3 Internal USB ports and 5 SATA ports.
Rear I/O	Audio In/Out, 6x SuperSpeed USB Type-A 5Gbps signaling rate, 1 RJ-45 Integrated LAN port (1GbE AMT) Optional: Flex I/O Module
Optional I/O	Flex I/O Module (Serial Port v3, Dual USB-A 3.2 Gen1, USB-C 3.2 Gen2, 10GbE single port, 2.5GbE LAN single port, 1 GbE single port, 1GbE Fiber single port LC, WiFi6 + BT5.2 WLAN w/ INTAnt) External Antenna
On-board RAID Support	SATA RAID 0 Striped Array SATA RAID 1 Mirrored Array SATA RAID 10 Striped/Mirrored SATA RAID 5 Parity Array
Chassis Dimensions (H x W x D)	Footprint: H: 15.2" (386 mm) W: 6.65" (169 mm) D: 17.5" (445 mm) Maximum: H: 15.2" (386 mm) W: 6.65" (169 mm) D: 18" (458.6 mm)
Packaged Dimensions	H: 22.5" (572 mm) W: 12.4" (314 mm) D: 22.2" (563 mm)
Rack Dimensions	4U
Weight	Exact weights depend upon configuration (System weight only). Minimum: 10.5 kg (23.2 lbs.) Typical: 12.6 kg (27.8 lbs.) Maximum:19.5 kg (42.9 lbs.)
Temperature	Operating: 5° to 40°C (40° to 104°F) ¹ Non-operating: -40° to 60°C (-40° to 140°F)
	¹ 40°C has been validated for configs up to a 220W CPU, 2x NVIDIA® A4000 graphics cards, 8x64GB of RAM, 4TB of M.2 storage, 4TB of HDD storage, and a 1125W PSU
Humidity	Operating: Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90%, non-condensing, 35° C maximum wet bulb
Maximum Altitude (non- pressurized) ⁶	Operating: 3,048m (10,000ft) Non-operating: 9,144m (30,000ft) NOTE: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1° C (1.8° F) per 305 m (1,000 feet) elevation increase
Power Supply	Choice of 90% Efficient Power Supplies: 1125W 775W 525W NOTE: not all configurations are supported on all power supplies. Configuration support depends on total system power budget and having sufficient number or type of PCIe supplemental power connectors. Confirm power supply and configuration support using configurator on hp.com.

Overview	
	 1125W supports up to 600W of auxiliary graphics power (dependent on system configuration)
	 775W supports up to 400W of auxiliary graphics power (dependent on system configuration)
	 525W supports up to 100W of auxiliary graphics power (dependent on system configuration)
	NOTE: updating graphics after purchase may require additional power distribution cables and/or auxiliary graphics adapters to support the new graphics configuration.
Workstation ISV Certifications	See the latest list of certifications at http://www.hp.com/united-states/campaigns/workstations/partnerships.html
Chipset	Intel® W790 chipset
Memory	8 DIMM slots, supporting up to 512GB, DDR5 4800 MT/s speed depending on the system configuration

Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-2400 Processors				
	Intel® Xeon® W7-2495X	Y	Ν		
	Intel® Xeon® W7-2475X	Y	Ν		
	Intel® Xeon® W5-2465X	Y	Ν		
	Intel® Xeon® W5-2455X	Y	Ν		
	Intel [®] Xeon [®] W5-2445	Y	Ν		
	Intel® Xeon® W3-2435	Y	Ν		
	Intel® Xeon® W3-2425	Y	Ν		
	Intel® Xeon® W3-2423	Y	Ν		

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	1TB 7200RPM SATA 3.5in Enterprise HDD ^{1,2}	Y	Y	WOR10AA
	2TB 7200RPM SATA 3.5in Enterprise HDD ^{1,2}	Y	Y	2Z274AA
	4TB 7200 RPM SATA 3.5in Enterprise HDD ^{1,2}	Y	Y	K4T76AA/AT
	8TB 7200RPM SATA 3.5in Enterprise HDD ^{1,2}	Y	Y	2Z273AA
	12TB 7200 RPM SATA-6G 3.5in Enterprise HDD ^{1,2}	Y	Y	5S461AA
PCIe Solid State				
Drives	Z Turbo 512GB PCIe-4x4 TLC SSD Module	Ŷ	Y	38T80AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T81AA
	Z Turbo 1TB 2280 PCIe-4x4 SED 0PAL2 TLC M.2 SSD Module	Y	Y	38T76AA
	Z Turbo 1TB PCIe-4x4 TLC SSD Module	Y	Y	38T77AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T79AA
	Z Turbo 2TB PCIe-4x4 TLC SSD Module	Y	Y	38T75AA
	Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module ⁶	Y	Y	5S496AA/AT
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module ⁶	Y	Y	5S497AA/AT
	Z Turbo 512GB PCIe-4x4 TLC Z4/Z6 Kit SSD	Y	Y	56Q73AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Y	Y	56Q74AA
	Z Turbo 1TB PCIe-4x4 TLC Z4/Z6 Kit SSD	Y	Y	56Q75AA
	Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Y	Y	5Z7E7AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Y	Y	56Q77AA
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD ⁶	Y	Y	5S4A1AA
	HP Z Turbo Drive Dual Pro			
	HP Z Turbo Drive Dual Pro PCIe-4x4 NVMe Carrier ³	Y	Y	56Q86AA
	Intel® Virtual RAID on CPU (Intel® VROC) for NVMe			

Supported Components

Intel VROC NVMe SSD Premium Ctlr Module ⁵	Ν	Y	3FJ81AA
Intel VROC NVMe SSD Standard Ctlr Module ⁴	Ν	Y	3FJ80AA

Note 1: For internal bay install, HDD option kits require separate purchase of 74Y88AA HP Z4 HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 74Y88AA HP Z4 HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.
Note 2: Up to (4) 3.5-inch 7200 rpm SATA drives: 1TB, 2TB, 4TB, 8TB, 12TB; 48TB max
Note 3: Kit includes dual pro carrier and heatsink. Requires separate purchase of ZTurbo PCIe 4x4 M.2 SSD modules.
Note 4: Enables RAID 0, 1 & 10
Note 5: Enables RAID 0, 1 & 10 plus RAID 5 with write hole closure options
Note 6: Available in June 2023

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB system disk (for Windows) is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable	HP DisplayPort To VGA Adapter	Ν	Y	AS615AA/AT	
Adapters	HP DisplayPort To VGA Adapter	Ν	Y	F7W97AA	
	HP GFX Pwr Cbl CPU-8p to CPU-8p	Y	Y	6J6H7AA	
	HP GFX Pwr Cbl CPU-8p to x2 PCIe 8p(6+2)	Y	Y	6J6H8AA	
	HP DisplayPort to HDMI Adapter	Y	Y	2JA63AA	
	HP (Bulk 12) miniDP-to-DP Adapter Cables	Ν	Y	2KW87A6	
	HP Single miniDP-to-DP Adapter Cable	Y	Y	2MY05AA	
	HP miniDP-to-DP Adapter (2-pack)	Y	Ν		
	HP miniDP-to-DP Adapter (4-pack)	Y	Ν		
	HP miniDP-to-DP Adapter (8-pack)	Y	Ν		
	HP DisplayPort To DVI Adapter (Bulk 90)	Ν	Y	FH973A6	
	NVIDIA NVLink 3-Slot Bridge	Y	Y	340L3AA	
	NVIDIA 3D Stereo Bracket	Ν	Y	KOA25AA	
Ultra High-End	NVIDIA® RTX 6000 Ada 48GB ^{1,3,4}	Y	Y	79C23AA/AT	?
Graphics	NVIDIA [®] RTX A6000 48GB ^{1,3}	Y	Y	2S6U3AA/AT	2
	NVIDIA [®] RTX A5000 24GB ¹	Y	Y	20X23AA/AT	2
	NVIDIA [®] Quadro [®] Sync II	Ν	Y	1WT20AA	
High-End Graphics	NVIDIA [®] RTX A4500 20GB ¹	Y	Y	5S458AA/AT	2
	NVIDIA [®] RTX A4000 16GB ^{1,*}	Y	Y	20X24AA/AT	2
	NVIDIA [®] Long-Life RTX A4000E 16GB ^{1,4,*}	Y	Y	6H7J7AA/AT	2
	AMD [®] Radeon TM Pro W6800 32GB ^{1,3}	Y	Y	340K7AA	2
Midrange Graphics	NVIDIA [®] RTX A2000 12GB ¹	Y	Y	5Z7D9AA/AT	2
	NVIDIA [®] Long-Life RTX A2000E 12GB ¹	Y	Ν		2
	NVIDIA [®] T1000 8GB ²	Y	Y	5Z7D8AA/AT	2
	NVIDIA [®] Long-Life T1000E 8GB ²	Y	Y	6V9V4AA/AT	2
	NVIDIA [®] T1000 4GB ²	Y	Y	20X22AA/AT	2
	AMD [®] Radeon TM Pro W6600 8GB ¹	Y	Y	340K5AA	2

Supported Components

Entry

AMD [®] Radeon TM RX 6700XT 12GB ¹	Y	Ν		1
NVIDIA [®] T400 4GB ²	Y	Y	5Z7E0AA/AT	2
AMD [®] Radeon [™] RX 6400 4GB	Y	Y	6Q3U4AA/AT	1
Intel Arc Pro A40 6GB ⁴	Y	Y	6E3Y8AA	1

*Only supported with 1125W PSU

Note 1: Single or dual graphics configuration requires the HP Z4 Fan and Front Card Guide. If configured as an after-market option, a separate purchase of the HP Z4 Fan and Front Card Guide 56Q79AA is required. If factory configured, the fan and front card guide is included.

Note 2: Dual graphics configuration requires the HP Z4 Fan and Front Card Guide. If configured as an after-market option, a separate purchase of the HP Z4 Fan and Front Card Guide 56Q79AA is required. If factory configured, the fan and front card guide is included.

Note 3: Dual graphics configuration requires the HP Z4 PCIe Retainer with Fans. If configured as an after-market option, a separate purchase of the HP Z4 PCIe Retainer with Fans 56Q84AA is required. If factory configured, the PCIe retainer with fans is included.

Note 4: Available in June 2023

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	16GB (1x16GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		
	32GB (2x16GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		
	64GB (4x16GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		
	64GB (2x32GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		
	128GB (8x16GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		1
	128GB (4x32GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		
	256GB (8x32GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		1
	256GB (4x64GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		
	512GB (8x64GB) DDR5 4800 DIMM ECC REG Memory	Y	Ν		1
	After Market Options				
	16GB DDR5 (1x16GB) 4800 DIMM ECC REG Memory	Y	Y	340K1AA	
	32GB DDR5 (1x32GB) 4800 DIMM ECC REG Memory	Y	Y	340K2AA	
	64GB DDR5 (1x64GB) 4800 DIMM ECC REG Memory	Y	Y	340K3AA	

NOTE 1: This memory configuration requires the 775W or 1125W PSU

Supported Components

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number
	HyperX Cloud Mix Wireless Gaming Headset	Ν	Y	4P5K9AA
	HyperX Cloud Core Gaming Headset	Ν	Y	4P4F2AA
	HyperX Cloud Flight Wireless Gaming Headset	Ν	Y	4P5L4AA
	HyperX Cloud Stinger Core Gaming Headset	Ν	Y	4P4F4AA
	HyperX SoloCast - USB Microphone	Ν	Y	4P5P8AA
	Integrated Realtek ALC3205-CG Audio	Y	Ν	

Optical and Removable Storage		Factory Configure d	Option Kit	Option Kit Part Number
	HP CRU QX428 Removable with 200mm Cable Frame/Carrier ^{1, 4}	Y	Y	56R11AA
	HP DX175 Removable HDD Frame/Carrier ^{2, 4}	Y	Y	1ZX71AA
	HP DX175 Removable HDD Spare Carrier ^{2, 4}	Ν	Y	1ZX72AA
	HP CRU Secure High Performance Storage Module with 2TB M.2 SSD ³	Y	Y	56Q87AA
	HP CRU Secure High Performance Storage Module with 1TB M.2 SSD ³	Y	Y	56Q88AA
	HP CRU Secure High Performance Storage Module with 512GB M.2 SSD ³	Y	Y	56Q89AA
	HP 9.5mm Slim DVD-ROM Drive	Y	Y	K3R63AA
	HP 9.5mm Slim BDXL Blu-Ray Writer Drive	Y	Y	K3R65AA
	HP 9.5mm Slim SuperMulti DVD Writer	Y	Y	K3R64AA

Note 1: Requires separate purchase of HP CRU Secure High Performance Storage (SHIPS) Module(s). Note 2: Only supports 4TB or lower capacity HDDs. Note 3: HP CRU SHIPS Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX428 Frame/Carrier). Note 4: Planned to be available in June 2023

Supported Components

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	HP 10GBase-T Flex Port	Y	Y	56Q71AA
	HP 2.5GbE LAN Flex Port	Y	Y	169K0AA/AT
	HP Flex 1GbE Single Port NIC	Y	Ν	
	HP 1GbE Fiber LC Single Flex Port	Y	Ν	20J15AA
	Intel® X550 10GBASE-T Dual Port NIC	Y	Y	1QL46AA
	Intel [®] I225-T1 Single Port 2.5GbE PCIe NIC	Y	Y	406L9AA
	Intel [®] Ethernet I350-T4 4-Port 1Gb NIC	Ν	Y	W8X25AA
	Intel® AX210 Wi-Fi 6 non-vPro +Bluetooth® 5.2 with Internal Antennae WLAN	Ν	Ν	
	Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Y	Y	1C7Q2AA
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Y	Y	6E3Y9AA/AT
	NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC ¹	Y	Y	436M8AA
	Intel AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External Antenna WLAN	Y	Y	340L7AA

Note1: 3rd party transceivers sold separately. You must have a transceiver installed to connect this card to a network.

Racking and		Factory	Option Kit	
Physical		Configured	Part Number	
Security	Z2 Mini/Z2 Tower/Z4/Z6 Depth Adjustable Fixed Rail Rack Kit	Ν	Y	2A8Y5AA

Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP 320K Wired Keyboard	Y	Y	9SR37AA/ET/UT
	HP 125 Wired Keyboard	Y	Y	266C9AA/ET/UT
	HP 975 USB+BT Dual-Mode Wireless Keyboard	Ν	Y	3Z726AA/ET/UT
	HP 455 Programmable Wireless Keyboard	Ν	Y	4R177AA/ET/UT/A6
	HP Wired Desktop 320MK Mouse and Keyboard	Ν	Y	9SR36AA/ET/UT
	HP 655 Wireless Keyboard and Mouse Combo	Ν	Y	4R009AA/ET/UT/A6
	HP Wired 320M Mouse	Y	Y	9VA80AA/ET/UT
	HP Creator 935 Black Wireless Mouse	Ν	Y	1D0K8AA/ET/UT
	HP 128 LSR Wired Mouse	Y	Y	265D9AA/ET/UT
	HP 125 Wired Mouse	Ν	Y	265A9AA/ET/UT
	HP Business Slim Smartcard Keyboard	Y	Y	Z9H48AA/AT

NOTE: Keyboard and Mouse are optional or add on features.

Supported Components

Other H

Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Z4 Fan and Front Card Guide Kit ⁵	Y	Y	56Q79AA
	HP Z4 Memory Cooling Solution ⁴	Y	Y	56Q81AA
	HP Z4 PCIe Retainer with Fans ⁵	Y	Y	56Q84AA
	HP 2.5in to 3.5in HDD Adapter Kit	Ν	Y	J5T63AA
	HP Internal Serial+PS/2 Port	Y	Y	56Q78AA
	HP Serial Port Flex IO v3	Y	Y	13L56AA/AT
	HP Dual USB-A 3.2 Gen1 Flex 2020	Y	Y	141J8AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Y	Y	141K6AA/AT
	HP Dual TBT4 PCIe x4 Low Profile Card ⁶	Y	Y	340L1AA
	HP USB 2.0 Type-A Port Adapter Kit ¹	Y	Y	79C24AA
	HP Type-C SuperSpeed USB 20Gbps Front IO v2 Premium Module	Y	Y	TBD
	HP 2.5in HDD/SSD 2-in-1 Optical Bay Bracket	Ν	Y	K4T74AA
	HP Z4 HDD Cable Kit ²	Ν	Y	74Y88AA
	HP Optical Bay HDD Mounting Bracket ³	Ν	Y	NQ099AA
	HP Z4 Dust Filter	Y	Y	3DY47AA
	HP SD 4 Card Reader Zx G4	Y	Y	2VK54AA
	HP C13 1.83m Power Cord Kit	Ν	Y	6Z1T9AA

Note 1: The HP USB 2.0 Type-A Port Adapter Kit 79C24AA has a single USB 2.0 type A connector.

Note 2: HP Z4 HDD Cable Kit 74Y88AA is required as a separate purchase for HDD option kit install into an interna bay. For external bay install, a separate purchase of 74Y88AA HP Z4 HDD Cable Kit & NQ099AA HP Optical Bay HD Mounting Bracket is required.

Note 3: NQ099AA HP Optical Bay HDD Mounting Bracket is required as a separate purchase for HDD option kits installed into an external bay.

Note 4: HP Z4 Memory Cooling Solution 56Q81AA is required as a separate purchase for after-market memory configurations using 32GB Registered DIMMs or greater. If configured from the factory, configurations using 32G Registered DIMMs or greater will include a memory cooling solution.

Note 5: HP Z4 Fan and Front Card Guide 56Q79AA and HP Z4 PCIe Retainer with Fans 56Q84AA are required for specific graphics configurations (see Graphics section).

Note 6: Available in June 2023

Software		Factory		Support Kit Notes 1 1
		Configured	Option Kit	Notes
	Data Science Stack	Y	Ν	1
	WSL2/Ubuntu Data Science Stack	Y	Ν	1
	Microsoft Office Home and Business Japan 2021	Y	Ν	

Note 1: Only available with Ubuntu and NVIDIA® graphics

Supported Components

Operating Systems Windows 11 Pro for Workstations^{1,2}

Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade)^{1,2,3} Ubuntu 22.04 LTS⁴ HP Linux[®]-ready

¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft. ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must bacl up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data. ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, H does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HF support website. https://support.hp.com/us-en/document/c05195282

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Z8 Fury G5 Workstation into the enterprise, such as PXE, remote recovery, remote configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates -Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Class 3 UEFI specification version 2.7
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and failsafe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides

Supported Components

the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.

- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery. Additional HP BIOS Features:
 - o Power-On password Helps prevent an unauthorized user from powering on the system.
 - Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
 - S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - Power to expansion connectors / slots
 - Most Wake events other than power buttons and WOL (Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - USB charging ports

HP Sure Start Gen7

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating.

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant ¹⁴ HP Image Assistant HP Desktop Support Utility HP Documentation HP Notifications HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics Windows HP Performance Advisor¹ myHP HP Easy Clean²⁰ HP Smart Health²¹ WSL/Ubuntu Data Science Stack HP Privacy Settings Touchpoint Customizer for Commercial

Supported Components

Manageability Features

HP Driver Packs² HP UWP Pack HP System Software Manager (SSM) HP Manageability Integration Kit Gen4³ HP Smart Support⁵ HP Client Catalog (download) HP Image Assistant (download) HP Cloud Recovery HP Client Management Script Library (download) HP BIOSphere Gen6 ¹³

Client Security Software

HP Client Security Suite Gen7⁴ including: (including Credential Manager, HP Password Manager⁶, HP Spare Key) HP Power On Authentication Microsoft Defender⁷

Security Management

HP Secure Erase ¹⁶ HP Wolf Pro Security Edition (optional) ¹⁸ HP Wolf Security for Business²² Includes: HP Sure Click¹¹ HP Sure Sense¹² HP Sure Run Gen5⁹ HP Sure Recover Gen4 ¹⁰ HP Sure Start Gen7⁸ HP Tamper Lock HP Sure Admin ¹⁷ HP Client Security Manager Gen 7⁴

¹ HP Performance Advisor Software - HP Performance Advisor is ready to help you get the most out of your HP Workstation from day one-and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor

² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html

⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.

⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.

⁷ Microsoft Defender Opt in and internet connection required for updates.

⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.

⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processor

¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back u important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi only available on PCs with Intel Wi-Fi Module

¹¹ HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details. ¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google ChromeTM, and ChromiumTM. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.
 ¹⁴ HP Support Assistant requires Windows and Internet access.

Supported Components

¹⁶ Secure Erase - For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clea sanitation method. HP Secure Erase does not support platforms with Intel® Optane.

¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagemer and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"?). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no futu software updates or HP Support.

²⁰ HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

²¹ HP Smart Health automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features

System Technical Specifications

System Board

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System Board Form Factor	Approximately 284.48mm x 297.	18mm (11.2x11.9 inches).
Processor Socket	Single LGA-4677	
CPU Bus Speed	DMI Gen4 x 8 lanes	
Chipset	Intel W790 Alder Lake - WS PCH	
Super I/O Controller	Nuvoton SIO21	
Memory Expansion Slots	8 DDR5 memory slots	
Memory Type Supported	DDR5, RDIMM (Registered) ECC	
Memory Modes	Non- Interleaved for single chann	el. Interleaved when multiple channels are populated
Memory Speed Supported	4800MT/s for 1DPC and 4400MH	z for 2DPC
Memory Protection	ECC on data	
Maximum Memory	512GB	
Memory Configuration (Supported)	16GB, 32GB and 64GB RDIMMs are (64GB RDIMM cannot be mixed w	e supported. ith other module capacities in the same system)
NVDIMM Memory	No	
PCI Express Connectors	Standard PCIe Slots	
Supported Drive Interfaces	 2 PCI Express Gen4 s 2 PCI Express Gen4 s M.2 Slots: 2 PCI Express Gen4 s Other PCIe Connections 	lot x16 mechanical/ x16 electrical (full height, full length) lot x16 mechanical/ x16 electrical (full height, full length) lot x4 mechanical/ x4 electrical (full height, half length) lot x4. (SlimSAS PCIe Gen4 x8) (supports two x4 M.2 devices via Number of SATA ports: 5 Intel® SATA controller: primary SATA On-board RAID Support Intel® VROC® SATA RAID 0, 1, 5, and 10 supported on Windows 10 and 1 RHEL 8.6 and later, SLE 15 SP4 and later Intel® VROC® NVMe RAID 0, 1, 5, and 10 supported with presence of
	Integrated Graphics Network Controller External SATA (eSATA) Serial 2nd Serial HD Integrated Audio	appropriate VROC upgrade module (after-market kits) on Windows 10 a 11, RHEL 8.6 and later, SLE 15 SP4 and later Factory Configured RAID: None No WGI219LM. WGI219LMLOM provides Management capabilities: WOL, PXE 2.1, DASH 1 and AMT No 1 internal header (requires optional Serial Port Adapter Kit) No Yes
USB Connector(s)	Front	Front I/O Entry:
		

System Technical Spe	cifications	
		4 USB 3.1 Gen1 Type-A (left-most port supports Battery Charging 1.2)
		Front I/O Premium: 2x USB 3.2 Gen2x2 Type-C [™] (Power Delivery 3.0) 2x USB 3.1 Gen1 Type-A (left-most port supports Battery Charging 1.2)
		 USB Type-C Ports provide 3 Amps @ 5 Volts Charging USB Type-A port provides 1.5 Amps @ 5 Volts
		 Standard USB Type-A Ports provide 900mA @ 5 Volts
	Rear	4x USB 3.1 Gen1 Type-A with USB hub and 2x USB 3.2 Gen 1 Type-A without hub. (Optional: 2x USB 3.0 Type-A (optional via Flex module) or 1x USB 3.1 Ge Type-C charging port (optional via Flex module).
	Internal	1 USB 3.2 Gen1 header, with a single 12-pin shrouded connector.This header supports a USB Media Card reader. 1 USB 2.0 single port header 1 USB 2.0 dual port header.
Flash ROM	Yes	
CPU Fan Header	Yes	
Memory Fan Header	Yes (dual header)	
Chassis Fan Header	1 front, one rear and one Aux Fa	n Header (dual)
Front PCI Fan Header	Yes (connects to AUX fan heade	r)
Front Control Panel/Speaker Header	Yes	
CMOS Battery Holder - Lithium	Yes	
Integrated Trusted Platform Module	Integrated TPM 2.0. Convertible to FIPS 140-2 Certif The TPM module is disabled who	ied Mode through firmware v15.21. ere restricted by law.
Power Supply Headers	Yes	
Power Switch, Power LED & Hard Drive LED Header	Yes	
Clear Password Jumper	Yes	
Keyboard/Mouse	USB and PS/2 (option)	

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows[®] 11 Professional 64 bit, Red Hat Linux 64[°] ²M.2 storage supports compatible devices up to 80mm

System Configurations				
Example Configuration #1	Processor Info	1x Intel Xeon w3-2425 6C 3.0GHz 4800 130W		
	Memory Info 16GB DDR5 (1x16GB) RegRAM			
	Graphics Info 1xNvidia T1000			
	Disks/Optical/Floppy	1x Internal 4TB M.2 + 1xDVDRW SATA		
	PSU 525W			
	Other	N/A		

System Technical Specifications

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	58.901	57.056	59.256	57.246	58.889	57.005
	Windows Busy Typ (SO)	201	.08	198.26		200.56	
	Windows Busy Max (SO)	513.	.451	206.345		205.432	
	Sleep (S3)	3.570	3.489	3.577	3.495	3.569	3.487
	Off (S5)	2.100	2.097	2.112	2.110	2.095	2.090
	Zero Power Mode (EuP)	0.153		0.193		0.152	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (SO)	200.97	194.67	202.18	195.32	200.988	194.558
	Windows Busy Typ (SO)	686.08 676.46		i.46	684.31		
	Windows Busy Max (SO)	728	728.508 704.255		.255	701.139	
	Sleep (S3)	12.180	11.904	12.204	11.924	12.177	11.897
	Off (S5)	7.165	7.154	7.206	7.199	7.148	7.131
	Zero Power Mode (EuP)	0.522		0.659		0.518	

Example Configuration #2	Processor Info	1x Intel Xeon w3-2435 8C 3.1GHz 4800 165W
	Memory Info	32GB DDR5 (2x16GB) RegRAM
	Graphics Info	1xNVIDIA Quadro A2000
	Disks/Optical/Floppy 1x 1TB SATA HDD + 1xInternal 4TB M.2 + 1xDVDRW SATA	
	PSU	775W
	Other	N/A

Energy Consumption	Consumption		VAC	230 VAC		100 VAC	
(Watts)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)	66.084	65.053	66.356	65.226	65.852	64.789
	Windows Busy Typ (SO)	258	3.55	254.89		257.86	
	Windows Busy Max (SO) 279.94		9.94	275.59 278.9		8.95	
	Sleep (S3)	3.916	3.808	3.925	3.812	3.912	3.801
	Off (S5)	22.36	2.216	2.248	2.224	2.234	2.213
	Zero Power Mode (EuP)	0.2	202	0.241		0.201	

Heat Dissipation		115	115 VAC		230 VAC		VAC
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (SO)	225.47	221.96	226.40	222.55	224.687	221.060
	Windows Busy Typ (SO)	882.17		869.68		879.81	
	Windows Busy Max (SO)	955.15		940.31		951.77	
	Sleep (S3)	13.361	12.992	13.392	13.006	13.347	12.969
	Off (S5)	7.629	7.560	7.670	7.588	7.622	7.550
	Zero Power Mode (EuP)	0.6	89	0.8	322	0.685	

System Technical Specifications

Example Configuration #3	Processor Info	1x Intel Xeon w5-2455X 12C 3.2GHz 4800 200W
	Memory Info	64GB DDR5 (4x16GB) RegRAM
	Graphics Info	1xNvidia Quadro A4000
	Disks/Optical/Floppy	2x 1TB SATA HDD + 1xInternal 4TB M.2 + 1xDVDRW SATA
	PSU	1125W
	Other	N/A

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	82.533	79.464	82.821	79.725	82.412	79.325
	Windows Busy Typ (SO)	400.06		396.25		399.23	
	Windows Busy Max (SO)	411.532		403.423		404.356	
	Sleep (S3)	4.403	4.332	4.409	4.335	4.400	4.328
	Off (S5)	2.411	2.395	2.418	2.400	2.406	2.390
	Zero Power Mode (EuP)	0.2	36	0.2	78	0.2	34

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (SO)	281.60	271.13	282.58	272.02	281.18	270.65
	Windows Busy Typ (SO)	1365.00		1352.00		1362.17	
	Windows Busy Max (SO)	1404.558		1376.883		1380.067	
	Sleep (S3)	15.023	14.780	15.043	14.791	15.012	14.767
	Off (S5)	8.226	8.171	8.250	8.177	8.209	8.154
	Zero Power Mode (EuP)	0.805		0.948		0.798	

Example Configuration #4	Processor Info	1x Intel w7-2495X 24C 2.5GHz 4800 225W
	Memory Info	128GB DDR5 (4x32GB) RegRAM
	Graphics Info	1xNVIDIA Quadro A6000
	Disks/Optical/Floppy	2x 4TB 7200 RPM SATA + 2x Internal 4TB M.2 + 1xDVDRW SATA
	PSU	1125W
	Other	N/A

Energy Consumption		115	115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows dle (S0)	596.25	592.56	595.23	596.25	592.56	595.23	
	Windows Busy Typ (SO)	608.784		600.412		601.314		
	Windows Busy Max (S0) 6.080		5.936 6.08)85			
	Sleep (S3)	2.361	2.356	2.370	2.361	2.356	2.370	
	Off (S5)	0.231	0.279	0.230	0.231	0.279	0.230	
	Zero Power Mode (EuP)	596	5.25	592	2.56	595	5.23	

System Technical Specifications

Heat Dissipation		115	115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (SO)	308.25	298.73	309.32	299.65	307.88	298.33	
	Windows Busy Typ (SO)	2034.40		3021.81		2030.92		
	Windows Busy Max (SO)	2077.779		2049.206		2052.285		
	Sleep (S3)	20.744	20.253	20.762	20.267	20.727	20.233	
	Off (S5)	8.055	8.038	8.086	8.067	8.048	8.025	
	Zero Power Mode (EuP)	0.788		0.951		0.784		

NOTE: The numbers in this table are from actual measurements on a single system. There will be some variation from unit to unit.

NOTE: The busy power number and associated BTU/hr number for each configuration will be a strong function of the actual application software run on the system. There can be a great deal of variation in this number.

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

Operating Voltage Range	90-269 VAC
Rated Voltage Range	100-240 VAC
Rated Line Frequency	50-60 Hz
Operating Line Frequency Range	47-66 Hz
ENERGY STAR [®] certified (Config Dependent)	Yes
CECP Compliant @ 220V	Yes
FEMP Standby Power Compliant	Yes, with Wake-on-LAN disabled: <1W in S5 - Power Off
Built-in Self Test (BIST) LED	Yes
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes
Hood Lock Header	Yes
ErP Lot 6- Tier 1 Compliance @ 230V (<1W in S5 - Power Off)	Yes
ErP Lot 6- Tier 2 Compliance @ 230V (<0.5W in S5 - Power Off)	Yes

System Technical Specifications

Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor)					
(Entry level)	Processor Info	1x Intel Xeon w3-2425 6C 3.0GHz 4800 130W			
	Memory Info	32GB (2x 16GB) DDR5 4800MHz RDIMM			
	Graphics Info	1xNVIDIA Quadro A2000			
	Disks/Optical	1x512GB SSD + 1xInternal 1TB M.2+ 1xDVDRW SATA			
	Power Supply	525W			

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)		
	Idle	3.4	15		
	Hard drive Operating (Drive Random Seek)	3.4	15		
	Active mode	3.3	15		

	Processor Info	1x Intel Xeon w5-2455X 12C 3.2GHz 4800 200W
(Mid-level)	Memory Info	128GB (8*16GB) DDR5 4800MHz RDIMM
	Graphics Info	1xNVIDIA Quadro A4000
	Disks/Optical	1x1TB HDD + 2xInternal 1TB M.2 SSD + 1xDVDRW SATA
	Power Supply	775W

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.4	16
	Hard drive Operating (Drive Random Seek)	3.4	16
	Active mode	3.4	16

System Configuration	Processor Info	1x Intel Xeon w7-2495X 24C 2.5GHz 4800 225W
(High-end)	Memory Info	512GB (8x64GB) DDR5 4800MHz RDIMM
	Graphics Info	2xNVIDIA Quadro A6000
	Disks/Optical	2x4TB HDD + 2xInternal 4TB M.2 SSD + 1xDVDRW SATA
	Power Supply	1125W

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.7	21
	Hard drive Operating (Drive Random Seek)	3.8	21
	Active mode	4.0	23

System Technical Specifications

Environmental Requirements	Temperature	Operating: 5° to 35° C (40° to 95° F) Non-operating: -40° to 60° C (-40° to 140° F)
	Humidity	Operating: 8% to 85% RH, non-condensing Non-operating: 8% to 90% RH, non-condensing
	Maximum Altitude	Operating: 3,048 m (10,000 feet) Non-operating: 9,144 m (30,000 feet)
	Dynamic	Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g NOTE: Values represent individual shock events and do not indicate repetitiv shock events
		Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz NOTE: Values do not indicate continuous vibration.
	Cooling	Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation, up 3048 m (10,000 feet)

Physical Security and Serviceability

Access Panel	Tool-less Includes system board and memory information
Optical Drive	Tool-less, Optical Drive requires a 5.25" bay carrier
Hard Drives	Tool-less
Expansion Cards	Tool-less
Processor Socket	Screw-in processor coolers
Blue User Touch Points	Yes, on tool-less internal chassis mechanisms
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Screw-in
Dual Color Power and HD LED on Front of Computer	Yes
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 4 seconds
Padlock Support	Yes (optional): Locks side cover and secures chassis from theft 7.0 mm (0.2756 in) diameter padlock loop rear of system
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot rear of system
Universal Chassis Clamp Lock Support	Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multipl units to be chained together when used with optional cable with threaded feature at rear of system
Chassis Interlock Sensor	Yes Sensor detects when the access panel has been removed. The access panel must be installed for the syste to power ON. Removal of the access panel during operation will power OFF the system.

System Technical Specifications

Solenoid Lock and Hood Sensor	Yes (optional) The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The Sensc detects when the access panel has been removed
Rear Port Control Cover	No
Serial, USB, Audio, Network, Enable/Disable Port Control	Yes
Power-On Password	Yes
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration.
3.3V Aux Power LED on System PCA	None
NIC LEDs (integrated) (Green & Amber)	Yes
CPUs and Heatsinks	A torx driver (T30) is needed to remove the processor heatsink. CPU attached to heatsink via tool-less cli
Power Supply Diagnostic LED	Yes
Front Power Button	Yes
Front Power LED	Yes
Front Hard Drive Activity LED	Yes
Front ODD Activity LED	Yes, on device
Internal Speaker	Yes
System/Emergency ROM Flash Recovery	Yes
Cooling Solutions	Air cooled forced convection
Power Supply Fans	80 mm x 80 mm x 25 mm (non-serviceable)
CPU Heatsink Fan	108 mm x 108 mm x 25 mm
Chassis Fan	Rear: 120 mm x 120mm x 25 mm Front (optional): 92 mm x 92 mm x 25 mm PCIe Retainer (optional based on configuration): Dual 80 mm x 80 mm x 20 mm
Memory Heatsink Fan	Dual 60 mm x 60 mm x 25 mm Blindmate (optional based on configuration)
Access Panel Key Lock	Yes, side panel barrel keylock (optional from the factory only)
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).
	 Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
Integrated Chassis Handles	Yes, front handle and dedicated rear recess
Power Supply	Requires T15 Torx or flat blade screwdriver
PCI Card Retention	Yes, rear (all), middle (all), front (full-length cards with extender, using Fan and Front Card Guide Kit)
Flash ROM	Yes
Diagnostic Power Switch LED on board	Yes
Clear Password Jumper	Yes
Clear CMOS Button	Yes

System Technical Specifications

CMOS Battery Holder	Yes
DIMM Connectors	Yes

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one countr and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise cla HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and i not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)
- Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpukmu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

Please contact techregshelp@hp.com

BIOS

PCIe 5.0 SupportFull BIOS support for PCI Express through industry standard interfaces. Supported speeds and slot
information vary.ATA/ATAPIAT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b

System Technical Specifications

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WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.
Replicated Setup	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
SMBIOS	System Management BIOS Reference Specification, Version 3.2
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes:
Remote ROM Flash	 NORMAL - normal temperature ranges. ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs. Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced	Allows the system to enter and resume from low power modes (sleep states).
Configuration and Power	Enables an operating system to control system power consumption based on the dynamic workload.
Management Interface)	Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 6.0 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time.
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bifurcation, speed) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
	control parameters are set according to detected nardware configuration for optimal acoustics.

System Technical Specifications

Pre-boot Diagnostics UEFI Specification Revision	(Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7
ACPI	Advanced Configuration and Power Management Interface, Version 6.0
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI Express	PCI Express Base Specification, Revision 2.0
•	PCI Express Base Specification, Revision 3.0
	PCI Express Base Specification, Revision 4.0
	PCI Express Base Specification, Revision 5.0
SATA	Serial ATA Specification, Revision 1.0a
	Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5
	Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
SPD	JEDEC JESD300-5
ТРМ	Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9672). Common Criteria EAL4+ certified.
	FIPS 140-2 Certification
	TCG TPM Certified products list:
	http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
UHCI	Universal Host Controller Interface Design Guide, Revision 1.1
USB	Universal Serial Bus Revision 1.1 Specification
	Universal Serial Bus Revision 2.0 Specification
	Universal Serial Bus Revision 3.1 Specification
	Universal Serial Bus Revision 3.2 Specification
	USB Battery Charging specification, Revision 1.2
CHENOC	USB Power Delivery specification Revision 3.0
SMBIOS	System Management BIOS Reference Specification, Version 3.2

Social and Environmental Responsibility

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

Energy Consumption (in accordance with US ENERGY STAR® test meth	od) 115VAC, 60Hz	230VAC, 50Hz	
System Configuration	The configuration used for the Energy model is based on a "Typically Configu	y Consumption and Declared Noise Emissions data for the Noteb Jured Notebook"?.	0(
Sustainable Impact Specifications	 US Federal Energy Management Program (FEMP) EPEAT[?] Gold registered worldwide TCO Certified China Energy Conservation Program (CECP) Ocean-bound plastic in system fans 40% post-consumer recycled plastic Contains 10% post-industrial recycled metal Internal Power Supply 90% efficient 		
	 IT ECO declaration ENERGY STAR® (energy- configurations-Windows or 	v-saving features available on selected	

System Technical Specifications

Normal Operation (Sort idle)	67.15 W	67.86 W
Normal Operation (Long idle)	64.93 W	64.85 W
Sleep	3.92 W	4.04 W
Off	2.23 W	2.30 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR[®] compliant product if offered within the model fam . HP computers marked with the ENERGY STAR[®] Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR[®] specifications for computers. If a model family does not offer ENERGY STAR[®] compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows[®] operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz
Normal Operation (Short idle)	228.98 BTU/hr	231.40 BTU/hr
Normal Operation (Long idle)	221.41 BTU/hr	221.14 BTU/hr
Sleep	13.37 BTU/hr	13.78 BTU/hr
Off	7.60 BTU/hr	7.84 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attain for one hour.

Declared Noise Emissions		
(in accordance with	Sound Power	Sound Pressure
ISO 7779 and ISO 9296)	(L _{WAd} , bels)	(L _{pAm} , decibels)
Typically Configured - Idle	3.4	15
Drive Random Seek	3.4	15
Active Mode	3.3	15

Longevity and Upgrading This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 1 PC card slot (type I/II)
- 1 ExpressCard/54 slot
- 1 IEEE 1394 Port
- 2 SODIMM memory slots
- Optional expansion base docking station
- 1 multi-bay II storage port
- Interchangeable HDD

Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.

Batteries	This battery in this product complies with EU Directive 2006/66/EC
	Battery size: CR2032 (coin cell)
	Battery type: Lithium Metal
	The battery in this product does not contain:
	 Mercury greater than5ppm by weight

Cadmium greater than 10ppm by weight

System Technical Specifications

	 Lead greater than 	40 ppm by weight	
Additional Information	2011/65/EC.		zardous Substances (RoHS) directive – lectrical and Electronic Equipment (WEEI
	Directive - 2002/96		lectrical and Electronic Equipment (WEE
	•	ompliance with California Proposition forcement Act of 1986).	65 (State of California; Safe Drinking
		ompliance with the IEEE 1680 (EPEAT) standard at the Gold level, see
		hing over 25 grams used in the produ 3% recycle-able when properly dispos	ct are marked per ISO11469 and ISO104: ed of at end of life.
Packaging Materials	External:	PAPER/Corrugated	At least 35% Recycled
		PAPER/Molded Pulp	100% Recycled
	Internal:	PLASTIC/Polyethylene low o - LDPE	density80% Recycled
	The corrugated paper pac	kaging materials contains at least 62	5% recycled content.
RoHS Compliance	the restrictions in the Eu Directive to our products	ropean Union (EU) Restriction of Ha	P has contributed to the development
	elimination of substance	s of concern. We have supported the certain phthalates-in future RoH	ortant role in promoting industry-wide ne inclusion of additional substances- S legislation that pertains to electrical
	requirements for virtually	jective to achieve worldwide compli / all relevant products by July 2013, ht to include further restricted subst	and we will continue to extend the
	To obtain a copy of the I	HP RoHS Compliance Statement, s	ee HP RoHS position statement.
Material Usage	HP General Specification f	for the Environment at following for the Environment at following for the following	in excess of regulatory limits (refer to th pplychain/
	 Cadmium Chlorinated Hydrod Chlorinated Paraffii Bis(2-Ethylhexyl) p Benzyl butyl phthalat Dibutyl phthalate (I Diisobutyl phthalat Formaldehyde Halogenated Dipher Lead carbonates an Lead and Lead com Mercuric Oxide Batt 	I Flame Retardants - may not be used carbons ns hthalate (DEHP) late (BBP) DBP) e (DIBP) nyl Methanes id sulfates pounds ceries	as flame retardants in plastics e designed to be frequently handled or

System Technical Specifications

	 carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly.
	 Design packaging materials for case of alsossempty. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product

System Technical Specifications

- 2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Manageability

Industry Standard Specifications Intel® Active Management Technology (AMT)

This product meets the following industry standard specifications for manageability functionality: • DASH 1.2 (via Intel® LAN on motherboard)

Intel[®] Active Management Technology (AMT) 16.10

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16.10 includes the following advanced management functions:

• Power Management (on, off, reset, graceful shutdown, sleep and hibernate)

o Support in Max Power Savings (Shutdown and Hibernate Modes)

- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.2 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel[®] vProTM Technology Yes, when configured with an Intel[®] vProTM supporting processor.

Technical Specifications - Stable & Consistent Offerings

Stable & Consistent Offerings

Global Series SKUs	breakthrough plat Offerings are built tested to work wit	nitment to hardware, software, and solution innovation, HP is proud to introduce this form configuration stability to HP Workstation customers. HP Stable & Consistent on the foundation of a carefully chosen set of hardware and software designed and h all HP Z Workstation platforms through their end of life. These components and their Workstation platform compatibility are outlined in this section.
Stable & Consistent Offerings	special programs, when you customi	stent Offerings are available worldwide to all HP Workstation customers-no no additional cost-no kidding. Simply select your hardware and software components ze your HP Workstation and be assured that you'll be able to buy that same ughout the lifecycle of the product.
Processors	Product #	Offering
	6M6F2AV	Intel Xeon W3-2423
	57M48AV	Intel Xeon W3-2435
Graphics	Product #	Offering
	6Z2Z0AV	NVIDIA Long-Life T1000E
	6Z2Y4AV	NVIDIA Long-Life RTX A2000E
	6Z2Y6AV	NVIDIA Long-Life RTX A4000E
	695F0AV	AMD Radeon RX 6400
	57K43AV	AMD Radeon Pro 6600
Storage	Product #	Offering
	57L12AV	Z Turbo 1TB PCIe-4x4 2280 TLC M.2 Solid State Drive
	57K65AV	1TB 7200RPM SATA 3.5in Enterprise

Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

Performance PCIe SSDs	Z 1
for HP Workstations	22
	SS

Z Turbo 512GB 2280 PCIe-4x4 TLC SSD

Capacity	512GB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	300TBW (TB Written)	
Reliability	1.5M hours	
Rated for 24/7/365 operation	No	
Interface	PCI Express 4.0 x4 electr	ical
Operating Temperature	e 32° to 158° F (0° to 70° C	.)
Performance	Sequential Read	up to 6400MB/s*
	Sequential Write	up to 3400MB/s*
	Random Read	up to 600K IOPS*
	Random Write	up to 600K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB	Capacity	512GB	
2280 PCIe-4x4 SED	Protocol	PCIe	
OPAL2 TLC M.2 SSD	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M hours	
	Rated for 24/7/365 operation	No	
	Interface	PCI Express 4.0 x4 electi	rical
	Operating Temperatur	e 32° to 158° F (0° to 70° (_)
	Performance	Sequential Read	up to 6400MB/s*
		Sequential Write	up to 3400MB/s*
		Random Read	up to 600K IOPS*
		Random Write	up to 600K IOPS*
	Self-Encrypting Drive Support	OPAL 2	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

Z Turbo 1TB	Capacity	1TB	
2280 PCIe-4x4 SED	Protocol	PCle	
OPAL2 TLC M.2 SSD Module	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability	1.5M hours	
	Rated for 24/7/365 operation	No	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperatur	e 32° to 158° F (0° to 70° (Z)
	Performance	Sequential Read	up to 6500MB/s*
		Sequential Write	up to 5000MB/s*
		Random Read	up to 800K IOPS*
		Random Write	up to 800K IOPS*
	Self-Encrypting Drive Support	OPAL 2	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB	Capacity	1TB	
2280 PCIe-4x4 TLC	Protocol	PCIe	
SSD	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability	1.5M hours	
	Rated for 24/7/365 operation	No	
	Interface	PCI Express 4.0 x4 electr	rical
	Operating Temperatur	e 32° to 158° F (0° to 70° ([)
	Performance	Sequential Read	up to 6500MB/s*
		Sequential Write	up to 5000MB/s*
		Random Read	up to 800K IOPS*
		Random Write	up to 800K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

2280 PCIe-4x4 TLC Protocol PCIe SSD Form Factor M.2 Controller NVMe	
Form Factor M.2	
Controller NVMe	
NAND Type 3D TLC	
Endurance 400TBW (TB Written)	
Reliability 1.5M hours	
Rated for 24/7/365 No operation	
Interface PCI Express 4.0 x4 electrical	
Operating Temperature32° to 158° F (0° to 70° C)	
Performance Sequential Read up to 6500M	B/s*
Sequential Write up to 5000M	B/s*
Random Read up to 800K IC)PS*
Random Write up to 800K IC)PS*
Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software.	6GB of
*Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 3 System disk (for Windows) is reserved for system recovery software.	6GB of
*Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Capacity 2TB	6GB of
 ^tActual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Capacity 2TB 2280 PCIe-4x4 SED Protocol PCIe OPAL2 TLC M.2 SSD 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Capacity 2TB 2280 PCle-4x4 SED Protocol PCle Form Factor M.2 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Capacity 2TB 2280 PCle-4x4 SED Protocol PCle Form Factor M.2 Controller NVMe 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Z Turbo 2TB Capacity Protocol PCIe Form Factor M.2 Controller NVMe NAND Type 3D TLC 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Z Turbo 2TB Capacity Protocol PCIe Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance S00TBW (TB Written) 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB 2280 PCle-4x4 SED Protocol PCle Protocol PCle Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance 500TBW (TB Written) 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Z Turbo 2TB Capacity Protocol PCIe Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance 500TBW (TB Written) Reliability 1.5M hours Rated for 24/7/365 No 	6GB of
 *Actual performance may vary. WOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB 2280 PCle-4x4 SED Protocol PCle Protocol PCle Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance 500TBW (TB Written) Reliability 1.5M hours Rated for 24/7/365 No 	6GB of
 *Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB 2280 PCle-4x4 SED Protocol PCle Protocol PCle Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance 500TBW (TB Written) Reliability 1.5M hours Rated for 24/7/365 No operation Interface PCI Express 4.0 x4 electrical 	
Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Capacity Protocol PCIe Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance S00TBW (TB Written) Reliability 1.5M hours Rated for 24/7/365 No operation Interface PCI Express 4.0 x4 electrical Operating Temperature32° to 158° F (0° to 70° C)	B/s
Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Z Turbo 2TB Capacity Protocol PCIe Form Factor N.2 Controller NVMe NAND Type 3D TLC Endurance SOOTBW (TB Written) Reliability 1.5M hours Rated for 24/7/365 No operation Interface PCI Express 4.0 x4 electrical Operating Temperatures ²⁰ to 158° F (0° to 70° C) Performance Sequential Read up to 6500M	B/s B/s*
Actual performance may vary. VOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 system disk (for Windows) is reserved for system recovery software. Z Turbo 2TB Capacity 2TB 2280 PCIe-4x4 SED Protocol PCIe DPAL2 TLC M.2 SSD Protocol PCIe Form Factor M.2 Controller NVMe NAND Type 3D TLC Endurance 500TBW (TB Written) Reliability 1.5M hours Rated for 24/7/365 No operation Interface PCI Express 4.0 x4 electrical Operating Temperature32° to 158° F (0° to 70° C) Performance Sequential Read up to 5000M	B/s B/s* DPS*

Self-Encrypting Drive Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 TLC SSD	Capacity	2TB	
	Protocol	PCIe	
330	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	500TBW (TB Written))
	Reliability	1.5M hours	
	Rated for 24/7/365 operation	No	
	Interface	PCI Express 4.0 x4 ele	ectrical
	Operating Temperat	ure32° to 158° F (0° to 7	0° C)
	Performance	Sequential Read	up to 6500MB/s*
		Sequential Write	up to 5000MB/s*
		Random Read	up to 800K IOPS*
		Random Write	up to 800K IOPS*
*Actual performance ma	iy vary.		
	B = 1 billion bytes. TB = 1 trillion s reserved for system recovery		acity is less. Up to 36GB of
Z Turbo 4TB	Capacity	4TB	
2280 PCIe-4x4 TLC M	^{.2} Protocol	PCIe	
SSD	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	600TBW (TB Written)	1
	Reliability	1.5M hours	
	Rated for 24/7/365 operation	No	

Interface PCI Express 4.0 x4 electrical

Operating Temperature32° to 158° F (0° to 70° C)

Performance	Sequential Read	up to 6500MB/s*
	Sequential Write	up to 5000MB/s*
	Random Read	up to 700K IOPS*
	Random Write	up to 700K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Z Turbo 4TB	Capacity	4TB		
2280 PCIe-4x4 SED	Protocol	PCIe		
OPAL2 TLC M.2 SSD	Form Factor	М.2		
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance	600TBW (TB Written)		
	Reliability	1.5M hours		
	Rated for 24/7/365 operation	Νο		
	Interface	PCI Express 4.0 x4 electrical		
	Operating Temperature32° to 158° F (0° to 70° C)			
	Performance	Sequential Read	up to 6500MB/s*	
		Sequential Write	up to 5000MB/s*	
		Random Read	up to 700K IOPS*	
		Random Write	up to 700K IOPS*	
	Self-Encrypting Drive Support	OPAL 2		
*Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.				

NOTE: available in June 2023

Z Turbo 512GB PCIe-	Capacity	512GB		
4x4 TLC Z4/Z6 Kit SSD	Protocol	PCIe		
	Form Factor	M.2		
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance	300TBW (TB Written)		
	Reliability	1.5M hours No		
	Rated for 24/7/365 operation			
	Interface	PCI Express 4.0 x4 electrical		
	Operating Temperature32° to 158° F (0° to 70° C)			
	Performance	Sequential Read	up to 6400MB/s*	
		Sequential Write	up to 3400MB/s*	
		Random Read	up to 600K IOPS*	
		Random Write	up to 600K IOPS*	

*Actual performance may vary.

Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Capacity	512GB		
	Protocol	PCIe		
	Form Factor	M.2		
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance	300TBW (TB Written)		
	Reliability	1.5M hours		
	Rated for 24/7/365 operation	Νο		
	Interface	PCI Express 4.0 x4 electrical		
	Operating Temperature32° to 158° F (0° to 70° C)			
	Performance	Sequential Read	up to 6400MB/s*	
		Sequential Write	up to 3400MB/s*	
		Random Read	up to 600K IOPS*	
		Random Write	up to 600K IOPS*	
	Self-Encrypting Drive Support	OPAL 2		

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB PCle-4x4 TLC Z4/Z6 Kit SSD	Capacity	1TB	
	Protocol	PCIe	
	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability	1.5M hours	
	Rated for 24/7/365 operation	No	
	Interface	PCI Express 4.0 x4 electrical	
	Operating Temperatur	e 32° to 158° F (0° to 70° ([)
	Performance	Sequential Read	up to 6500MB/s*
		Sequential Write	up to 5000MB/s*
		Random Read	up to 800K IOPS*
		Random Write	up to 800K IOPS*

*Actual performance may vary.

Z Turbo 1TB 2280	Capacity	1TB		
PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Protocol	PCIe		
1 LG WI.2 24/20 KIT 33D	Form Factor	M.2		
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance	400TBW (TB Written)		
	Reliability	1.5M hours		
	Rated for 24/7/365 operation	Νο		
	Interface	PCI Express 4.0 x4 electrical		
	Operating Temperature32° to 158° F (0° to 70° C)			
	Performance	Sequential Read	up to 6500MB/s*	
		Sequential Write	up to 5000MB/s*	
		Random Read	up to 800K IOPS*	
		Random Write	up to 800K IOPS*	
	Self-Encrypting Drive Support	OPAL 2		

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2	Capacity	2TB		
	Protocol	PCIe		
TLC M.2 Z4/Z6 Kit SSD	Form Factor	M.2		
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance	500TBW (TB Written)		
	Reliability	1.5M hours		
	Rated for 24/7/365 operation	Νο		
	Interface	PCI Express 4.0 x4 electrical		
	Operating Temperature32° to 158° F (0° to 70° C)			
	Performance	Sequential Read	up to 6500MB/s*	
		Sequential Write	up to 5000MB/s*	
		Random Read	up to 800K IOPS*	
		Random Write	up to 800K IOPS*	
	Self-Encrypting Drive Support	OPAL 2		

*Actual performance may vary.

	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2	Capacity	4TB		
		Protocol	PCIe		
	TLC M.2 Z4/Z6 Kit SSD	Form Factor	M.2		
		Controller	NVMe		
		NAND Type	3D TLC		
	Endurance	600TBW (TB Written)			
	Reliability	1.5M hours			
	Rated for 24/7/365 operation	Νο			
		Interface	PCI Express 4.0 x4 electrical		
		Operating Temperature32° to 158° F (0° to 70° C)			
		Performance	Sequential Read	up to 6500MB/s*	
			Sequential Write	up to 5000MB/s*	
			Random Read	up to 700K IOPS*	
		Random Write	up to 700K IOPS*		
	Self-Encrypting Drive Support	OPAL 2			

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

SATA Hard Drives for HP	1TB 7200RPM SATA	Consoitu	1 T D	
Workstations	3.5in Enterprise HDD	Capacity	1TB	
WUIKSLALIUIIS		Protocol	SATA	
		Form Factor	3.5"	
		Controller	AHCI	
		Reliability	2.0M hours	
		Rated Power On Hours	8760/yr	
		Annualized Failure Rate (based on Rated POH)	<0.62%	
		Rated for 24/7/365 operation	YES	
		Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
		Interface	Serial ATA (6.0Gb/s), NCQ enabled	
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s *	
		Buffer	128MB	
		Cache	Adaptive	
		Seek Time (typical reads	s, Single Track	0.32 ms *
		includes controller overhead, including	Average	7.45 ms *
		settling)	Full Stroke	14.2 ms *
		Rotational Speed	7,200 rpm	

Technical Specifications - Hard Drives

	Logical Blocks		1,953,525,168	
	Operating Temperatur		C)	
	Performance	Sequential Read	up to 226MB/s*	
		Sequential Write	up to 226MB/s*	
	vary. = 1 billion bytes. TB = 1 trillion by reserved for system recovery so		ty is less. Up to 36GB of	
2TB 7200RPM SATA	Capacity	2TB		
3.5in Enterprise HDD	Protocol	SATA		
	Form Factor	3.5"		
	Controller	AHCI		
	Reliability	2.0M hours		
	Rated Power On Hours	8760/yr		
	Annualized Failure Rate (based on Rated POH)	<0.62%		
	Rated for 24/7/365 operation	YES		
	Height	1 in; 2.54 cm		
	Width	Media Diameter	3.5 in; 8.9 cm	
		Physical Size	4 in; 10.17 cm	
	Interface	Serial ATA (6.0Gb/s), NO	Q enabled	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s *		
	Buffer	128MB		
	Cache	Adaptive		
	Seek Time (typical reads	s, Single Track	0.7 ms *	
	includes controller overhead, including	Average	8.5 ms *	
	settling)	Full Stroke	15.7 ms *	
	Rotational Speed	7,200 rpm		
	Logical Blocks	3,907,029,168		
	Operating Temperatur	e 41° to 131° F (5° to 55°	C)	
	Performance	Sequential Read	up to 226MB/s*	
		Sequential Write	up to 226MB/s*	

*Actual performance may vary.

4TB 7200 RPM SATA	Capacity	4TB	
3.5in Enterprise HDD	Protocol	SATA	
	Form Factor	3.5"	
	Controller	AHCI	
	Reliability	2.0M hours	
	Rated Power On Hours	8760/yr	
	Annualized Failure Rate (based on Rated POH)	<0.62%	
	Rated for 24/7/365 operation	YES	
	Height	1 in; 2.54 cm	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0Gb/s), NCQ enabled	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s *	
	Buffer	256MB	
	Cache	Adaptive	
	Seek Time (typical reads	s, Single Track	0.7 ms *
	includes controller overhead, including	Average	8.5 ms *
	settling)	Full Stroke	15.7 ms *
	Rotational Speed	7,200 rpm	
	Logical Blocks	7,814,037,168	
	Operating Temperatur	e 41° to 131° F (5° to 55°	C)
	Performance	Sequential Read	up to 226MB/s*
		Sequential Write	up to 226MB/s*

*Actual performance may vary.

8TB 7200RPM SATA	Capacity	8TB	
3.5in Enterprise HDD	Protocol	SATA	
	Form Factor	3.5"	
	Controller	AHCI	
	Reliability	2.0M hours	
	Rated Power On Hours	8760/yr	
	Annualized Failure Rate (based on Rated POH)	<0.62%	
	Rated for 24/7/365 operation	YES	
	Height	1 in; 2.54 cm	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0Gb/s), N	CQ enabled

Synchronous Transfer Rate (Maximum)	Up to 600MB/s *	
Buffer	256MB	
Cache	Adaptive	
Seek Time (typical reads	5,Single Track	0.7 ms *
includes controller overhead, including	Average	8.5 ms *
settling)	Full Stroke	15.7 ms *
Rotational Speed	7,200 rpm	
Logical Blocks	15,628,053,168	
Operating Temperatur	e 41° to 140° F (5° to 60°	C)
Performance	Sequential Read	up to 226MB/s*
	Sequential Write	up to 226MB/s*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

12TB 7200 RPM SATA- 6G 3.5in Enterprise HDD	Capacity	12TB		
	Protocol	SATA		
סטח	Form Factor	3.5"		
	Controller	AHCI		
	Reliability	2.0M hours		
	Rated Power On Hours	8760/yr		
	Annualized Failure Rate (based on Rated POH)	<0.62%		
	Rated for 24/7/365 operation	YES		
	Height	1 in; 2.54 cm		
	Width	Media Diameter	3.5 in; 8.9 cm	
		Physical Size	4 in; 10.17 cm	
	Interface	Serial ATA (6.0Gb/s), NCQ enabled		
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s *		
	Buffer	256MB		
	Cache	Adaptive		
	Seek Time (typical reads	s, Single Track	0.7 ms *	
	includes controller overhead, including	Average	8.5 ms *	
	settling)	Full Stroke	15.7 ms *	
	Rotational Speed	7,200 rpm		
	Logical Blocks	23,437,770,752		
	Operating Temperature41° to 140° F (5° to 60° C)			
	Performance	Sequential Read	up to 226MB/s*	
		Sequential Write	up to 226MB/s*	

*Actual performance may vary.

Technical Specifications - Hard Drives

Technical Specifications - Graphics

GRAPHICS

24GB

NVI DIA ®	Form Factor	
RT X ^T M		
60 00 Ad		
a		
48		Full-Height Dual Slot (4.4"? Height x 10.5"? Length)
GB		Weight: 1230 grams / 2.71 lbs (with extender)
	Max Power Consumption	Power: 300 Watts
		Cooling: Active
	GPU Memory	48GB GDDR6 memory ECC
		Memory Bandwidth: Up to 960 GB/s
		Memory Width: 384 bits
	Connectors	4x DisplayPort 1.4a
		Quadro Sync II connector
		Stereo Sync
		Requires CEM 5.0 16-pin auxiliary power adapter
	Maximum Resolution	7680x4320 @ 120Hz
	Bus Type	PCI Express 4.0 x16
	Available Graphics Drivers	Windows 11
		Windows 10
		Linux [®] 64-bit
	NOTE: available in June 2023	

NVIDIA[®] RTX[™] A6000 **Form Factor** Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 1230 grams / 2.71 lbs (with extender) 48GB Power: 300 Watts **Max Power Consumption Cooling: Active** 48GB GDDR6 memory **GPU Memory** ECC optional Memory Bandwidth: Up to 768 GB/s Memory Width: 384 bit Connectors 4x DisplayPort 1.4a Quadro Sync II connector **NVLink**[®] Stereo Sync Requires 8-pin auxiliary power **Maximum Resolution** 7680x4320@120Hz **Bus Type** PCI Express 4.0 x16 Available Graphics Drivers Windows 11 Windows 10 Linux[®] 64-bit NVIDIA[®] RTX[™] A5000 **Form Factor** Full-Height Dual Slot (4.4"? Height x 10.5"? Length)

Weight: 1049 grams + 80 grams extender

Technical Specifications - Graphics

Max Power Consumption	Power: 230W Cooling: Active
GPU Memory	24GB GDDR6 memory ECC optional Memory Bandwidth: Up to 768 GB/s Memory Width: 384 bit
Connectors	4x DisplayPort 1.4a Quadro Sync II connector NVLink® Stereo Sync Requires 8-pin auxiliary power
Maximum Resolution	7680x4320 @ 120Hz
Bus Type	PCI Express 4.0 x16
Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX A4500 20GB	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 1049 grams + 80 grams extender
	Max Power Consumption	Power: 200W Cooling: Active
	GPU Memory	20GB GDDR6 memory Memory Bandwidth: Up to 640 GB/s Memory Width: 320 bit
	Connectors	4x DisplayPort 1.4a Quadro Sync II connector NVLink® Stereo Sync Requires 8-pin auxiliary power
	Maximum Resolution	7680x4320 @ 120Hz
	Bus Type	PCI Express 4.0 x16
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
NVIDIA [®] RTX A4000 16GB	Form Factor	Full-Height Single Slot (4.4"? Height x 9.5"? Length) Weight: 500 grams
	Max Power Consumption	Power: 140W Cooling: Active
	GPU Memory	16GB GDDR6 memory Memory Bandwidth: Up to 448 GB/s

7680x4320 @ 120Hz

PCI Express 4.0 x16

Memory Width: 256 bit 4x DisplayPort 1.4a

Quadro Sync II connector

Requires 6-pin auxiliary power

Stereo Sync

Connectors

Bus Type

Maximum Resolution

	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
NVIDIA® Long-Life RTX A4000E 16GB	Form Factor	Full-Height Single Slot (4.4"? Height x 9.5"? Length) Weight: 500 grams
	Max Power Consumption	Power: 140W Cooling: Active
	GPU Memory	16GB GDDR6 memory Memory Bandwidth: Up to 448 GB/s Memory Width: 256 bit
	Connectors	4x DisplayPort 1.4a Quadro Sync II connector Stereo Sync Requires 6-pin auxiliary power
	Maximum Resolution	7680x4320 @ 120Hz
	Bus Type	PCI Express 4.0 x16
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
	NOTE: available in June 20	023
AMD® Radeon TM Pro W6800 32GB	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 850 grams
	Max Power Consumption	Power: 261W Cooling: Active
	GPU Memory	32GB GDDR6 memory Memory Bandwidth: Up to 512 GB/s Memory Width: 256 bit
	Connectors	6x mini-DisplayPort 1.4 Requires 8-pin+6-pin auxiliary power
	Maximum Resolution	7680x4320 @ 60Hz
	Bus Type	PCI Express 4.0 x16
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit

rechnical Specificatio	recipical Specifications - Graphics				
NVIDIA® RTX A2000 12GB	Form Factor	Half-Height Dual Slot (2.713"? Height x 6.6"? Length) Weight: 306 grams			
	Max Power Consumption	Power: 70W Cooling: Active			
	GPU Memory	12GB GDDR6 memory Memory Bandwidth: Up to 288 GB/s Memory Width: 192 bit			
	Connectors	4x mini-DisplayPort 1.4a			
	Maximum Resolution	7680x4320 @ 120Hz			
	Bus Type	PCI Express 4.0 x16			
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit			
NVIDIA® Long-Life RTX A2000E 12GB	Form Factor	Half-Height Dual Slot (2.713"? Height x 6.6"? Length) Weight: 306 grams			
	Max Power Consumption	Power: 70W Cooling: Active			
	GPU Memory	12GB GDDR6 memory Memory Bandwidth: Up to 288 GB/s Memory Width: 192 bit			
	Connectors	4x mini-DisplayPort 1.4a			
	Maximum Resolution	7680x4320 @ 120Hz			
	Bus Type	PCI Express 4.0 x16			
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit			
NVIDIA® T1000 8GB	Form Factor	Half-Height Single Slot (2.713"? Height x 6.137"? Length)			
		Weight: 132.6 grams			
	Max Power Consumption	Power: 50W Cooling: Active			
	GPU Memory	8GB GDDR6 memory Memory Bandwidth: Up to 160 GB/s Memory Width: 128 bit			
	Connectors	4x mini-DisplayPort 1.4a			
	Maximum Resolution	7680x4320 @ 120Hz			
	Bus Type	PCI Express 3.0 x16			
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit			

NVIDIA® Long-Life T1000E 8GB	Form Factor	Half-Height Single Slot (2.713"? Height x 6.137"? Length) Weight: 132.6 grams
	Max Power Consumption	Power: 50W Cooling: Active
	GPU Memory	8GB GDDR6 memory Memory Bandwidth: Up to 160 GB/s Memory Width: 128 bit
	Connectors	4x mini-DisplayPort 1.4a
	Maximum Resolution	7680x4320 @ 120Hz
	Bus Type	PCI Express 3.0 x16
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
NVIDIA® T1000 4GB	Form Factor	Half-Height Single Slot (2.713"? Height x 6.137"? Length) Weight: 132.6 grams
	Max Power Consumption	Power: 50W Cooling: Active
	GPU Memory	4GB GDDR6 memory Memory Bandwidth: Up to 160 GB/s Memory Width: 128 bit
	Connectors	4x mini-DisplayPort 1.4a
	Maximum Resolution	7680x4320 @ 120Hz
	Bus Type	PCI Express 3.0 x16
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
AMD® Radeon TM Pro W6600 8GB	Form Factor	Full-Height Single Slot (4.38"? Height x 9.50"? Length) Weight: 132.6 grams
	Max Power Consumption	Power: 122W Cooling: Active
	GPU Memory	8GB GDDR6 memory Memory Bandwidth: Up to 224 GB/s Memory Width: 128 bit
	Connectors	4x DisplayPort 1.4 Requires 6-pin auxiliary power
	Maximum Resolution	7680x4320 @ 60Hz
	Bus Type	PCI Express 4.0 x16 (x8 electrical)
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit

AMD® Radeon™ RX 6700XT 12GB	Form Factor	Full-Height Dual Slot (4.30"? Height x 10.0"? Length) Weight: 684 grams
	Max Power Consumption	Power: 238W Cooling: Active
	GPU Memory	12GB GDDR6 memory Memory Bandwidth: Up to 384 GB/s Memory Width: 192 bit
	Connectors	4x DisplayPort 1.4 1x HDMI Requires 8-pin+6-pin auxiliary power
	Maximum Resolution	7680x4320 @ 60Hz
	Bus Type	PCI Express 4.0 x16
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
NVIDIA® T400 4GB	Form Factor	Half-Height Single Slot (2.713"? Height x 6.137"? Length) Weight: 123.5 grams
	Max Power Consumption	Power: 30W Cooling: Active
	GPU Memory	4GB GDDR6 memory Memory Bandwidth: Up to 80 GB/s Memory Width: 64 bit
	Connectors	3x mini-DisplayPort 1.4a
	Maximum Resolution	7680x4320 @ 120Hz
	Bus Type	PCI Express 3.0 x16
	Available Graphics Drivers	Windows 11 Windows 10

Technical Specifications - Graphics

AMD® Radeon™ RX 6400 4GB	Form Factor	Half-Height Single Slot (4.4"? Height x 10.5"? Length) Weight: 155 grams
	Max Power Consumption	Power: 50W Cooling: Active
	GPU Memory	4GB GDDR6 memory Memory Bandwidth: Memory Width:
	Connectors	1x DisplayPort 1.4a 1x HDMI
	Maximum Resolution	7680x4320 @ 60Hz
	Bus Type	PCI Express 4.0 x4
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
Intel® Arc Pro A40 6GB	Form Factor	Half-Height Single Slot (2.7"? Height x 6.6"? Length) Weight: 220 grams
	Max Power Consumption	Power: 50W Cooling: Active
	GPU Memory	4GB GDDR6 memory Memory Bandwidth: 192GB Memory Width: 96 bit
	Connectors	4x mini- DisplayPort 1.4
	Maximum Resolution	7680x4320 @ 60Hz
	Bus Type	PCI Express 4.0 x8
	Available Graphics	Windows 11
	Drivers	Windows 10

Notes for all graphics cards:

- Some graphics and GPU compute cards can consume a great deal of power, thus combinations of cards with other components may exceed a particular power supply's output capability.
- Some graphics and GPU compute cards require supplemental power cables.
- Not all chassis/PSU configurations have enough supplemental power cables of the correct type for all graphics configurations.

Refer to the Power Supply section within Overview for more information.

Technical Specifications - Optical and Removable Storage

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim Blu-Ray	Description	9.5mm height, tray-load	
Writer	Mounting Orientation	Either horizontal or vertical	L
	Interface Type	SATA/ATAPI	
	Dimensions (WxHxD)	128 x 9.5 x 127mm	
	Supported Media Types	BD-ROM BD-R BD-RE DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-R DVD-RW CD-R	
	Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB standard
		Blu-ray	25 GB (single-layer) 50 GB (dual-layer) 100/128 GB (BDXL)
		Full Stroke DVD	< 230 ms (seek)
		Full Stroke CD	< 220 ms (seek)
		Blu-ray	< 230 ms (seek) (Full Stroke Blu-ray)
		Startup Time	(Time to drive ready from tray loading) BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 25S / 28S BD-RE (SL/DL) 25S / 28S DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) 25S / 25S DVD-R (SL/DL) 25S / 25S DVD-RW 25S DVD+R (SL/DL) 25S / 25S DVD+R (SL/DL) 25S / 25S DVD+RW 25S DVD+RW 25S DVD+RW 25S DVD+RW 25S DVD-RW 25S
	Maximum Data Transfer Rates	CD ROM Read	CD-ROM, CD-R Up to 24X CD-RW Up to 24X
		DVD ROM Read	DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X
		Blu-ray	BD-ROM Up to 6X BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X

Technical Specifications - Optical and Removable Storage

	BD-RE SL/DL Up to 6X
Source	SATA DC power receptacle
DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
DC Current	5 VDC -900 mA typical, 2000mA maximum
Temperature	41° to 122° F (5° to 50° C)
Relative Humidity	10% to 80%
Maximum Wet Bulb Temperature	84° F (29° C)
Red Hat® Enterprise Linux® SUSE Linux® Enterprise Des Ubuntu 20.04, 22.04 LTS	Nindows 7 Professional 64-bit, (RHEL) 8, 9 Desktop/Workstation ktop 15 s device. Native support is provided by the
SATA data/power cable, ins As Blu-ray is a new format o	Vriter, 5.25" ODD Bay adapter/carrier, slim tallation guide containing new technologies, certain disc, bility and/or performance issues may arise, and do
	DC Power Requirements DC Current Temperature Relative Humidity Maximum Wet Bulb Temperature Windows 11, Windows 10, W Red Hat® Enterprise Linux® SUSE Linux® Enterprise Des Ubuntu 20.04, 22.04 LTS No driver is required for this operating system.

may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drive and players. Flawless playback on all systems is not guaranteed.

HP 9.5mm Slim DVD Writer	Description Mounting Orientation Interface Type Dimensions (W×H×D) Supported Media Types	9.5mm height, tray-load Either horizontal or vertica SATA/ATAPI 128 x 9.5 x 127mm DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DL DVD-RW CD-R CD-R	l
	Disc Capacity	DVD-ROM Full Stroke DVD Full Stroke CD	8.5 GB DL or 4.7 GB standard < 200 ms (seek) < 200 ms (seek)
	Maximum Data Transfer Rates	CD ROM Read DVD ROM Read	CD-ROM, CD-R Up to 24X CD-RW Up to 24X DVD+RW Up to 8X DVD-RW Up to 8X

Technical Specifications - Optical and Removable Storage

		DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X
Power	Source	SATA DC power receptacle
	DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
	DC Current	5 VDC -< 800 mA typical, <1600 mA maximum
Operating Environmental	Temperature	41° to 122° F (5° to 50° C)
(all conditions non-	Relative Humidity	10% to 80%
condensing)	Maximum Wet Bulb Temperature	84° F (29° C)
Operating Systems Supported	Windows 11, Windows 10, Windows 7 Professional 64-bit, Windows Vista Business 64*, Windows 2000. Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation SUSE Linux® Enterprise Desktop 15 Ubuntu 20.04, 22.04 LTS * No driver is required for this device. Native support is provided by the	
Kit Contents	operating system HP SATA DVD Writer drive,	
NOTE: Actual speeds may commercially available DV storage of your original ma	vary. No support for DVD-R D movies or other copyrigh aterial and other lawful use r, double-layer discs burne	AM (DVD Writer). Does not permit copying of t protected materials. Intended for creation and s. Double Layer discs can store more data than d with this drive may not be compatible with many

existing	single-layer DVD driv	ves and players.

HP 9.5mm Slim DVD-ROM	Description	9.5mm height, tray-load	
	Mounting Orientation	Either horizontal or vertical	l
	Interface Type	SATA/ATAPI	
	Dimensions (WxHxD)	128 x 9.5 x 127mm	
	Disc Capacity	DVD-ROM	Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB
	Access Times	DVD-ROM Single Layer	< 110 ms (typical)
		CD-ROM Mode 1	< 110 ms (typical)
		Full Stroke DVD	< 230 ms (typical)
		Full Stroke CD	< 220 ms (typical)
	Power	Source	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
		DC Current	5 VDC -< 800 mA typical, <1600 mA maximum
(all condition	Operating Environmental	Temperature	41° to 122° F (5° to 50° C)
	(all conditions non-	Relative Humidity	10% to 80%
	condensing)	Maximum Wet Bulb Temperature	84° F (29° C)

Technical Specifications - Optical and Removable Storage

Operating Systems Supported	Windows 11, Windows 10, Windows 8.1, Windows 7 Professional 64-bit Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation SUSE Linux® Enterprise Desktop 15 Ubuntu 20.04, 22.04 LTS		
	No driver is required for this device. Native support is provided by the operating system.		

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25"" ODD Bay adapter/carrier, slim SATA data/power cable, installation guide

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

HP 10GBase-T Flex Port	Connector	RJ-45 (Single Port)
	Cabling	Twisted Pair Cabling, up to 100 meters
	Controller	Marvell AQC113C
	Memory	128KB Tx Buffer, 192KB Rx Buffer on-chip
	Data Rates Supported	10/100/1000 Mbps and 2.5/5/10 Gbps
	Compliance	802.3 - 2018, 802.1AS-2011
	Bus Architecture	PCI Express and SMBus
	Data Transfer Mode	PCIe-based interface for active state operation (S0 state) a
	Power Requirement	Requires 0.7V VDD, 1V, and 2V for analog, 3.3V for VDDIO
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex
	Network Transfer Rate	10GBASE-T 5GBASE-T 2.5GBASE-T 1000BASE-T 100BASE-TX 10BASE-Te
	Management Capabilities	WOL, PXE, UEFI,
	Kit Contents	HP 10GBase-T Flex Port NIC Module
HP 2.5GbE LAN Flex Port	Connector	RJ45 (Single Port)
	Cabling	Copper twisted pair, Cat5e up to 100 meters
	Controller	Intel [®] I225-V
	Memory	4 Tx and 4 Rx Queues, Jumbo Frames up to 9KB and withou
	Data Rates Supported	10/100/1000Mbps and 2.5Gbps BASE-T
	Compliance	IEEE 802.3, 802.3u (auto-negotiation), 802.3ab, 1588, 802. 802.3br, 802.3az
	Bus Architecture	PCIe G2x1
	Data Transfer Mode	PCIe-based interface for active state operation (S0 state) aı low power state)
	Power Requirements	2.2 Watts
	Network Transfer Mode	Automatic link configuration for speed duplex and flow cor
	Network Transfer Rate	2500BASE-T 1000BASE-T 100BASE-TX (Half-duplex supported) 10BASE-Te (Half-duplex supported)
	Management Capabilities	WOL, PXE, UEFI, Intel vPro® support with appropriate Intel buffers, UDP/TCP/IP Checksum Offload, SCTP receive and tr

rechilded Specifications Re		
HP 1GbE Fiber LC Single Flex Port	Connector	LC (Little Connector) Fiber (Single Port)
	Cabling	LC Fiber Cabling
	Controller	AT-29M2
	Data Rates Supported	1GBASE-SX
	Bus Architecture	USB 3.1G1
	Power Requirements	Up to 3.3 Watts
	Network Transfer Mode	1GBASE-SX
	Network Transfer Rate	1GBASE-SX
	Management Capabilities	Wake on LAN, Digital Diagnostic Monitoring
	Kit Contents	HP 1GbE Fiber LC Single Flex Port NIC
HP Flex 1GbE Single Port NIC	Connector	RJ45 (Single Port)
	Cabling	1GbE over Category 5e (or better) up to 100m
	Controller	Realtek RTL8153
	Data Rates Supported	10/100/1000 Mbps
	Bus Architecture	USB3.1G1, USB2
	Power Requirements	Requires 3.3V (integrated regulators for core Vdc)
	Network Transfer Mode	Full-duplex; Half-duplex
	Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps
	Management Capabilities	Wake on LAN, PXE, UEFI
	Kit Contents	HP 1GbE Single Flex Port
Intel® X550 10GBASE-T Dual Port	Connector	2 x RJ-45
NIC	Cabling	Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m
	Controller	Intel X550-AT2
	Memory	Jumbo Frames up to 15.5KB, 64 Tx and 64Rx Queues per po transmit buffers
	Data Rates Supported	100Mbps (BASE-TX), 1Gbps (BASE-T, 2.5Gbps, 5Gbps, 10Gb
	Compliance	802.1q (VLAN), 802.1Qbb, 802.1p, 802.1Qaz
	Bus Architecture	PCIe 3x4
	Data Transfer Mode	PCIe Gen 3 x4 based interface
	Power Requirements	3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps
	Boot ROM Support	Yes
	Network Transfer Mode	Auto negotiation between 1GbE, 2.5GbE, 5GbE and 10GbE
	Management Capabilities	DMI 2.0 Support, Windows Management Instrumentation (\ Multi-mode I/O Virtualization, VxLAN, VMDq, VLAN support

	Kit Contents	Intel® X550 10GBASE-T Dual Port NIC
	Connector	DL 45 (Cingle Dort)
Intel® I225-T1 Single Port 2.5GbE PCIe NIC	Connector	RJ-45 (Single Port)
	Cabling Controller	Cat5e (or better) up to 100m Intel® Ethernet I225 Controller
	Memory Data Datas Supported	Jumbo Frames up to 9.5KB, 4 Tx and Rx Queues,
	Data Rates Supported	2.5GbE, 1GbE, 100MbE, 10MbE
	Compliance	IEEE 802.3 auto negotiation, 802.3x, 802.3z
	Bus Architecture	PCIe Gen 3.1x1
	Data Transfer Mode	PCIe-based interface for active state operation
	Power Requirements	1.9 Watts (typical)
	Management Capabilities	WOL, PXE 2.1, Power Management Protocol Offload (proxyi Power Management,
	Kit Contents	Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracl and Low-profile bracket included Product Literature
Intel® Ethernet I350-T4V2 4-Port	Connector	4x RJ-45 (Quad Port)
1Gb NIC	Cabling	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps up to 100m
	Controller	Intel [®] I350
	Memory	Jumbo Frames up to 9.5KB, 8 Tx/Rx Queue pairs per port, №
	Data Rates Supported	10Mbps, 100Mbps, 1Gbps
	Compliance	IEEE 802.3 auto negotiation, 802.3, 802.3u, 802.3ab, 802.3 implementation, 802.3az EEE
	Bus Architecture	PCI Express 2.1 x4
	Data Transfer Mode	PCIe-based interface for active state operation
	Power Requirements	5W
	Network Transfer Mode	Multi-speed, full, and half-duplex
	Network Transfer Rate	10BASE-T 100BASE-Tx 1000BASE-T
	Management Capabilities	WOL, PXE 2.1, UEFI, Power Management Protocol Offload (p State Power Management, VLAN, ACPI
	Kit Contents	Intel® Ethernet I350-T4V2 4-Port 1Gb NIC with full-height b Low-profile bracket included
Intel® AX210 Wi-Fi 6 + Bluetooth®	Connector	Wireless
5.2 Flex Port NIC with Internal	Cabling	N/A
Antennae	Controller	Intel [®] AX210
	Data Rates Supported	Wi-Fi 6 (2.4GHz/5GHz)
	Compliance	Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a/ WPA3, Wi-Fi Direct, and Wi-Fi Agile Multiband IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, I, k

	Bus Architecture	PCIe G3x1 for WLAN, USB3.1G1 for BT
	Management Capabilities	Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MS(AKA, EAP-AKA')
		Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP UEFI
	Kit Contents	Intel [®] AX210 Wi-Fi 6 + Bluetooth [®] 5.2 Flex Port NIC Installation Instructions
	* Wireless access point and Inter is backwards compatible with pr	rnet service required and sold separately. Availability of public v rior 802.11 specs.
Intel® AX210 Wi-Fi 6E non-vPro +	Connector	Wireless
Bluetooth [®] 5.2 with External	Cabling	N/A
Antennae WLAN	Controller	Intel® AX210
	Data Rates Supported	Wi-Fi 6e (2.4GHz/5GHz/6GHz)
	Compliance	Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a WPA3, Wi-Fi Direct, and Wi-Fi Agile Multiband IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, I,
	Bus Architecture	PCIe G3x1 for WLAN, USB3.1G1 for BT
	Management Capabilities	Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MS AKA, EAP-AKA') Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP UEFI
	Kit Contents	Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 PCIe NIC External Dipole Antenna Installation Instructions
		iter, sold separately to function in the 6GHz band. Availability o r 802.11 specs. And available in countries where Wi-Fi 6E is sup
Allies Telesis AT-2914SX/LC 1GB LC	Connector	LC Fiber (Single Port)
Fiber NIC	Cabling	50/125 μm (core/cladding) multimode fiber optic cable up 62.5/125 μm (core/cladding) multimode fiber optic cable ι
	Memory	Jumbo Frames up to 9.6KB
	Data Rates Supported	1000SX (1GbE Fiber at 850nm Wavelength)
	Compliance	IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICk
	Bus Architecture	PCIe x1
	Data Transfer Mode	PCIe-based interface
	Power Requirements	1.5 Watts (typical)
	Network Transfer Rate	1000SX only (1GbE Fiber at 850nm Wavelength)
	Management Capabilities	UEFI, Smart Load Balancing and failover, Link aggregation IEEE 802.3ad-draft static, VLAN Support
	Kit Contents	Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC with low-pro bracket included

Allied Telesis AT-2911T/2-901 Dual	Connector	2 x RJ-45 (Dual Port)
Port 1GbE NIC	Cabling	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps up to 100m
	Memory	17 Rx and 16 Tx queues
	Data Rates Supported	10/100/1000 Mbps
	Compliance	IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X) 802.3ab (10/100/1000T) RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK
	Bus Architecture	PCIe 2x1
	Data Transfer Mode	PCIe-based interface
	Power Requirements	2.4 Watts (typical)
	Management Capabilities	VLAN support, Link aggregation LACP, Link aggregation sm (SLB), iSCSI boot support, Windows Management Instrumeı
	Kit Contents	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC with low bracket included

NVIDIA® Mellanox® ConnectX-6 DX	Connector	2 x SFP28 Transceiver Cage (Dual Port)*
Dual Port 10/25GbE SFP28 NIC	Cabling	Depends on transceiver pairing. Typically OM4 or higher MI Transceivers.
	Controller	ConnectX6-DX
	Memory	256Mbit SPI Quad Flash Device
	Data Rates Supported	1/10/25GbE
	Compliance	 IEEE 802.3by 25 Gigabit Ethernet IEEE 802.3ae 10 Gigabit Ethernet IEEE 802.3ap based auto-negotiation and KR startup IEEE 802.3ad, 802.1AX Link Aggregation IEEE 802.1Q, 802.1P VLAN tags and priority IEEE 802.1Qau (QCN) Congestion Notification IEEE 802.1Qaz (ETS) IEEE 802.1Qbb (PFC) IEEE 802.1Qbg IEEE 1588v2 Jumbo frame support (9.6KB) Safety: CB/cTUVus/CE EMC: CE/FCC/VCCI/RCM RoHS Compliant KCC CAN ICES-3 (B) NM EN 55035/55032 (Morocco) UKCA
	Bus Architecture	PCIe Gen 4 x8
	Data Transfer Mode	PCI Express - stores and accesses Ethernet fabric connectic
	Power Requirements	11.5 Watts (typical)

Technical Specifications - Networking and Communications

Network Transfer Rate

1Gbps, 10Gbps, 25Gbps

NOTE: Network Transfer Rate depends on transceiver mode

Kit Contents

NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP:

Summary of Changes

Date of change:	Version History:		Description of change:
March 1, 2023	From v1 to v2	Changed	Optical and Removable Storage, Networking and Communications sections and Changed Format
March 30, 2023	From v2 to v3	Changed	Image page 1
April 1, 2023	From v3 to v4	Changed	Format
April 6, 2023	From v4 to v5	Changed	PCIe Solid State Drives section

title

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